

In The Abstract

Please amend the Abstract as follows:

-A cooling stage for a semiconductor substrate and a method for utilizing such cooling stage for improved cooling of a semiconductor substrate. In the cooling stage, a pedestal that has a substantially planar top surface is equipped with a first plurality of circular grooves concentrically formed in the top surface and a second plurality of linear grooves formed in radial directions emanating from a center of the top surface in fluid communication with the first plurality of circular grooves to allow a cooling fluid to flow therethrough when a semiconductor substrate is positioned on the top surface of the stage.-

In The Claims

Claims 16, 18, 19 and 20 have been cancelled without prejudice and withdrawn from further consideration by the Examiner.